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United States Patent [19]

Ishihara

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[54] **IC MODULE**

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[73] Assignee: **Kabushiki Kaisha Toshiba**, Kawasaki, Japan

[**] Term: **14 Years**

[21] Appl. No.: **62,838**

[22] Filed: **Nov. 27, 1996**

[30] **Foreign Application Priority Data**

May 29, 1996 [JP] Japan .... 8-15398 U

[51] **LOC (6) Cl.** **14-02**

[52] **U.S. Cl.** **D14/114**; D14/117

[58] **Field of Search** D14/114, 117, D14/107; 235/378–380, 492, 487; 257/731, 669

[56] **References Cited**

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[57] **CLAIM**

The ornamental design for an IC module, as shown and described.

DESCRIPTION

FIG. **1** is a front, bottom and right side perspective view of an IC module, showing my new design;

FIG. **2** is a front elevational view thereof;

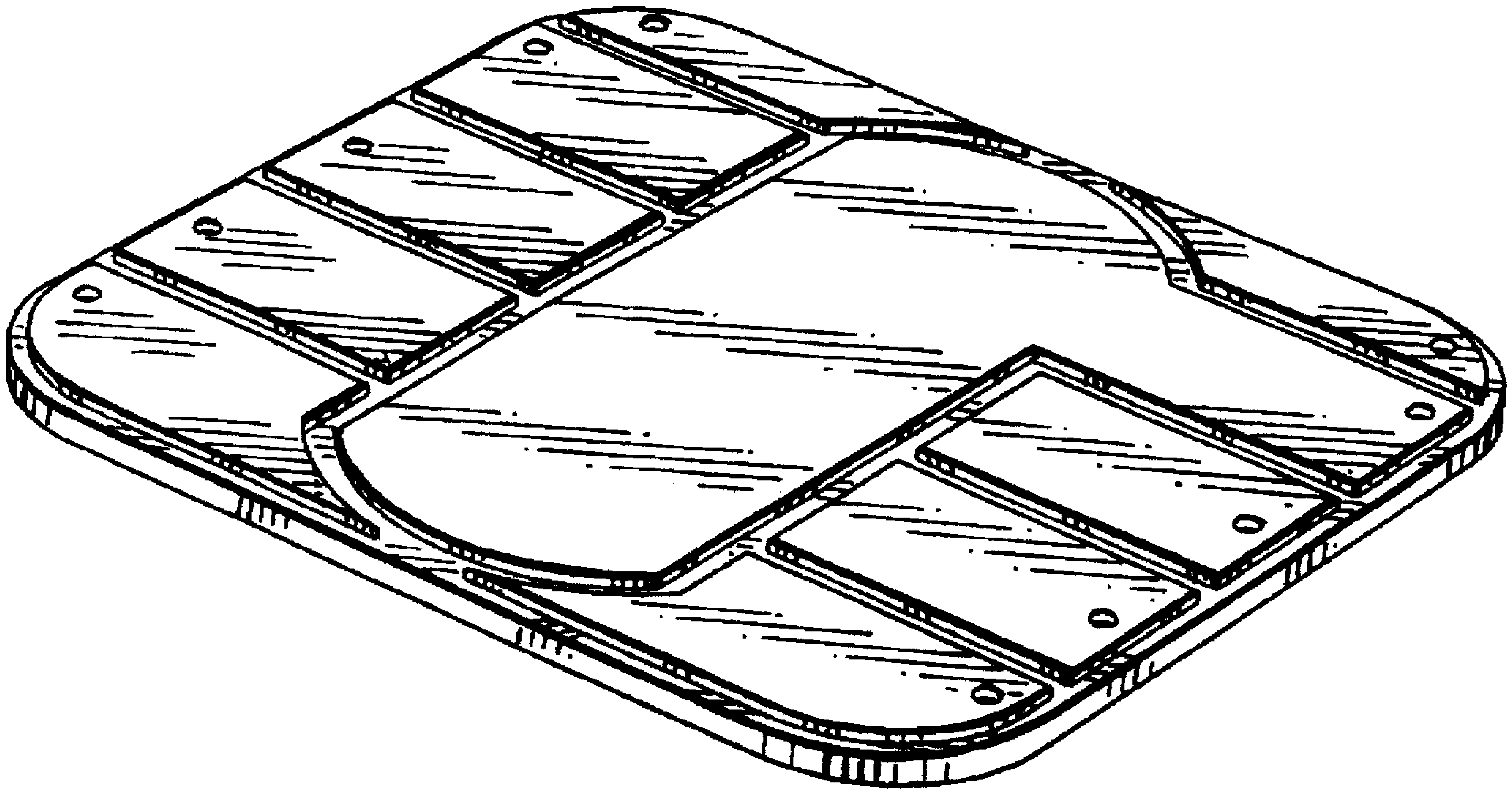
FIG. **3** is a right side elevational view thereof, the opposite side being a mirror image;

FIG. **4** is a top plan view thereof;

FIG. **5** is a bottom plan view thereof; and,

FIG. **6** is a rear elevational view thereof.

1 Claim, 1 Drawing Sheet



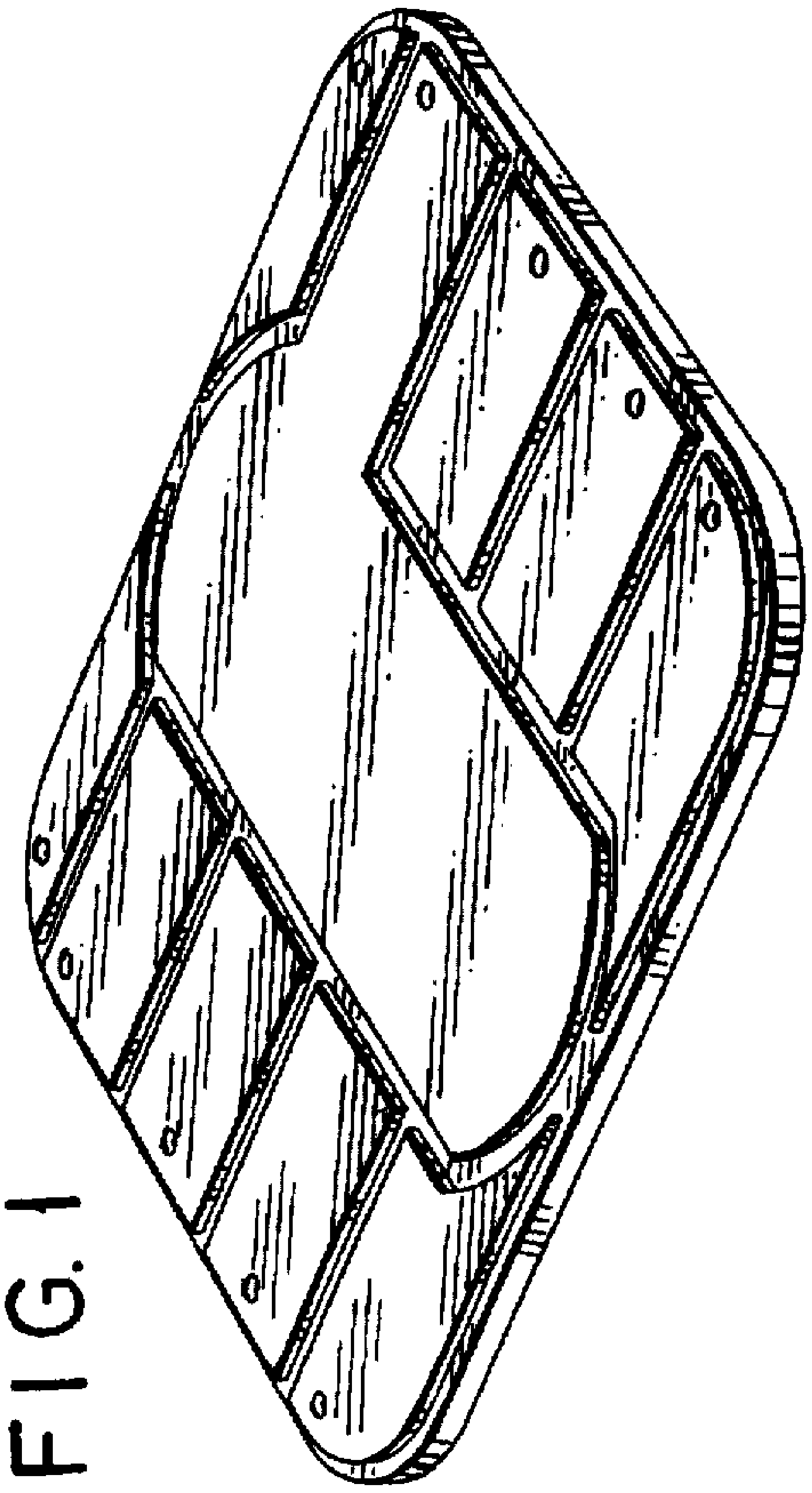


FIG. 1

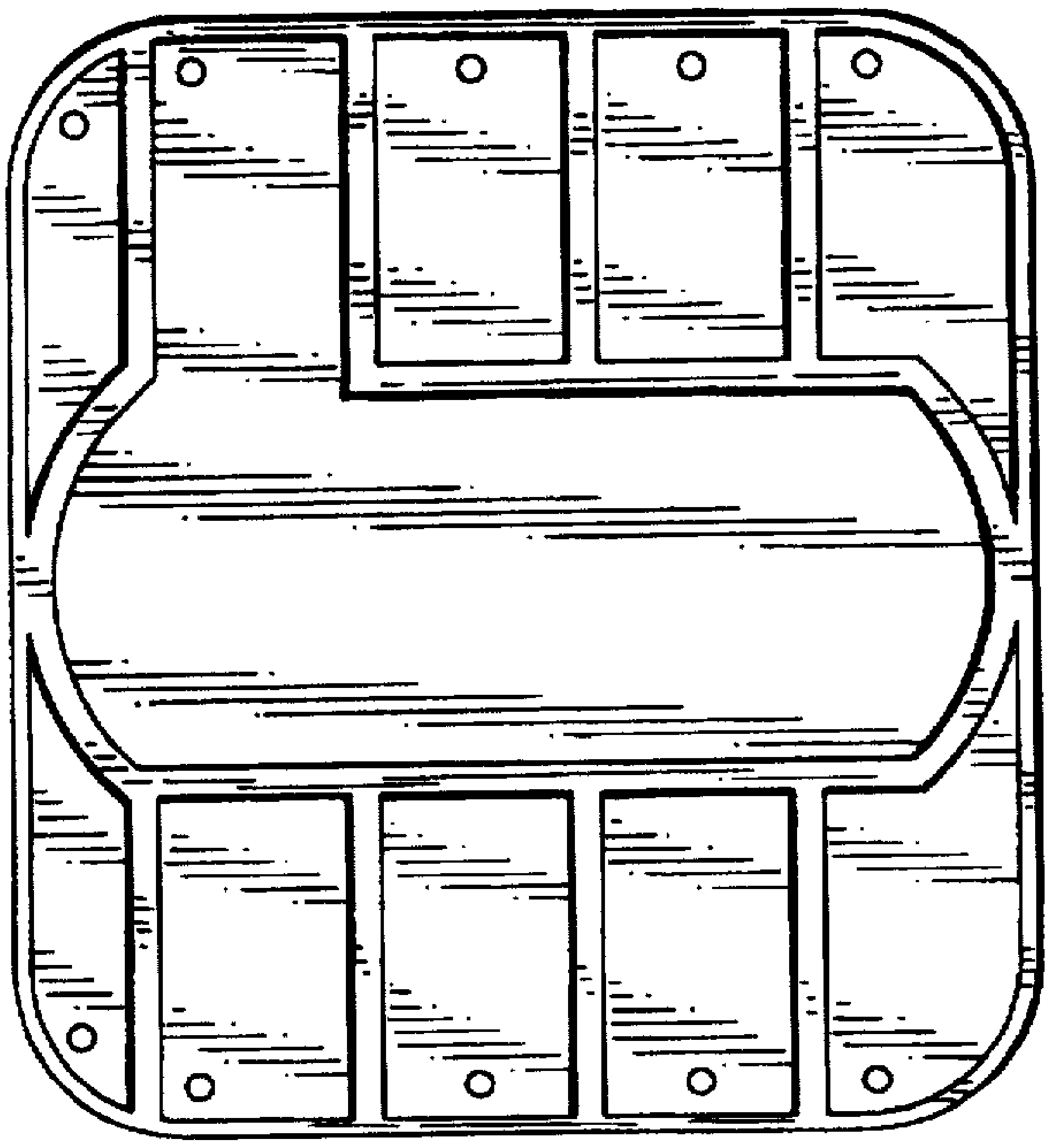


FIG. 2

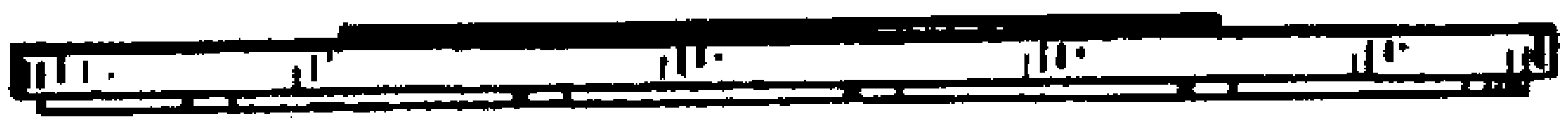


FIG. 3

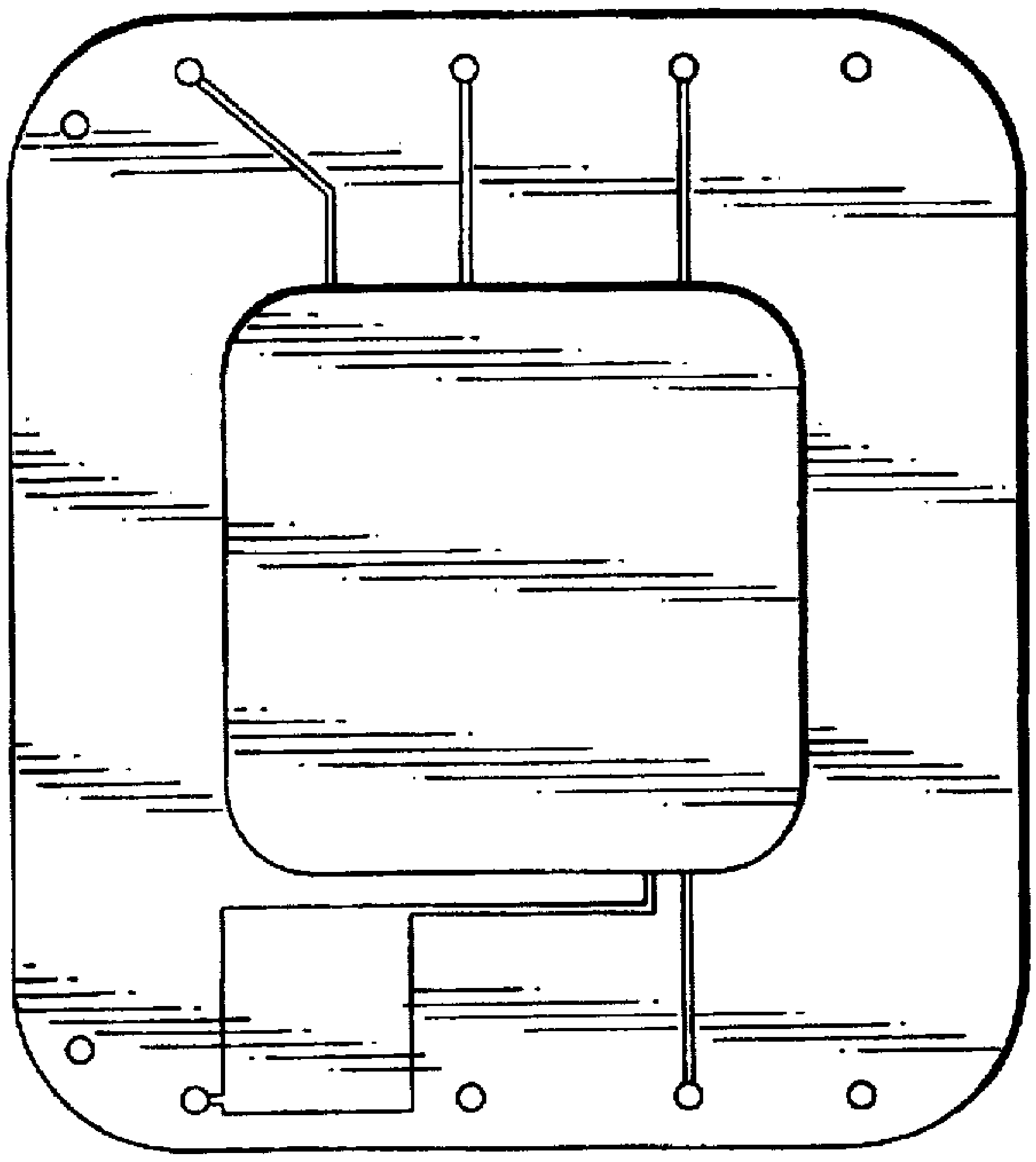


FIG. 4

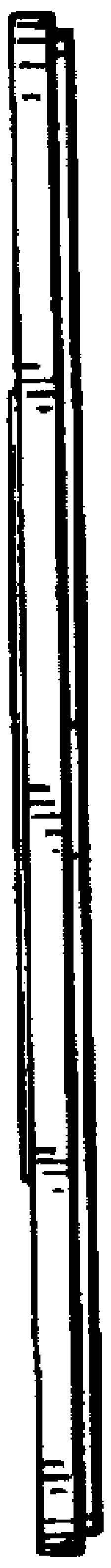


FIG. 5

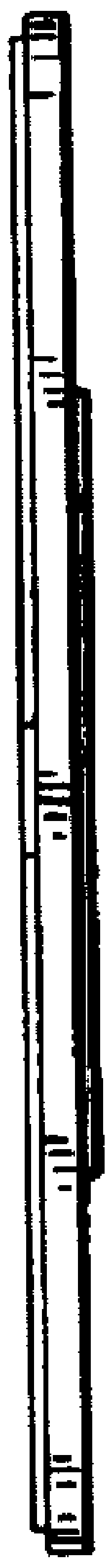


FIG. 6